



1281-01  
28/12  
Docket No.: M4065.0468/P468  
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:  
Phillip E. Byrd, et al.

Application No.: 09/941,761

Filed: August 30, 2001

For: METHOD AND STRUCTURE FOR  
TEMPORARILY ISOLATING A DIE FROM  
A COMMON CONDUCTOR TO  
FACILITATE WAFER LEVEL TESTING

Group Art Unit: 2812

Examiner: Not Yet Assigned

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SUBMISSION OF FORMAL DRAWINGS

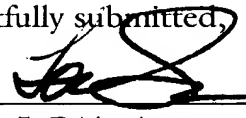
Commissioner for Patents  
Washington, DC 20231

Dear Sir:

Submitted herewith is one set (eight sheets, Figures 1-11) of formal drawings for filing in the above-identified Patent application. Kindly substitute the enclosed formal drawings for the informal drawings submitted with the originally filed application.

Dated: December 17, 2001

Respectfully submitted,

By   
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